

800nA,500mA,Low-Dropout Voltage Regulator

Features

- Low quiescent current : 800nA
- Wide input voltage range : 1.3V to 6V
- High output current : 500mA
- Low dropout voltage : 130mV at 100mA
- PSRR : 60dB/1kHz
- Fixed output voltages : 1.2V, 1.5V, 1.8V, 2.5V, 2.8V, 3.0V, 3.3V, 3.6V
- Output voltage tolerance : $\pm 1\%/\pm 2\%$
- Current limit protection
- Short circuit protection
- Thermal shutdown protection
- Available packages : SOT23-5,SOT89-3,DFN1 \times 1, SOT23-3

Applications

- Wearable electronics
- Smoke detector and sensor
- Gas, heat and water meters
- Blood glucose meters and pulse oximeters

Description

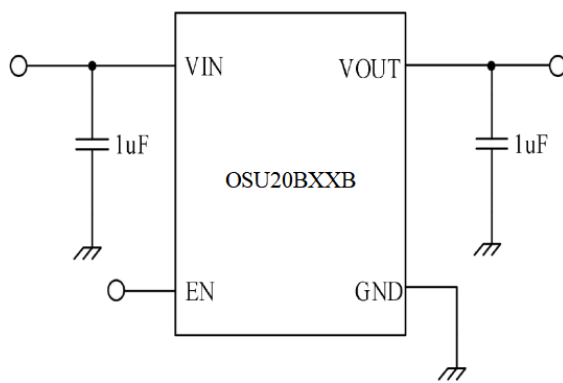
The OSU20BXXA/B series is an ultra-small, low dropout (LDO) linear regulator that can source 500mA of output current. The OSU20BXXA/B has fast response to input voltage transient and load current transient, and ensures no overshoot voltage during OSU20BXXA/B startup and short circuit recovery.

The OSU20BXXA/B series has thermal shutdown, current limit, and short circuit protections for added safety.

The OSU20BXXA/B series contains eight fixed output voltages of 1.2V, 1.5V, 1.8V,2.5V, 2.8V, 3.0V, 3.3V,3.6V.

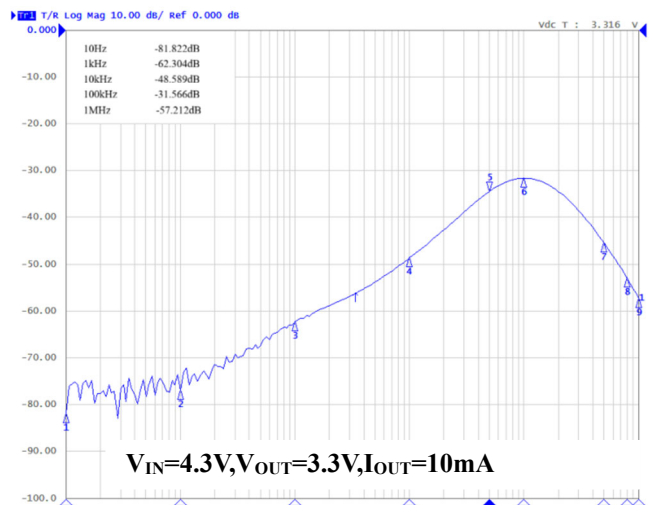
PART NUMBER	PACKAGE	BODY SIZE(NOM)
OSU20BXXA/BTG	SOT23-5	2.9mm*2.8mm
OSU20BXXA/BTS	SOT89-3	4.5mm*4.2mm
OSU20BXXA/BTN	DFN1 \times 1	1.0mm*1.0mm
OSU20BXXA/BTE	SOT23-3	2.9mm*2.8mm

Typical Application

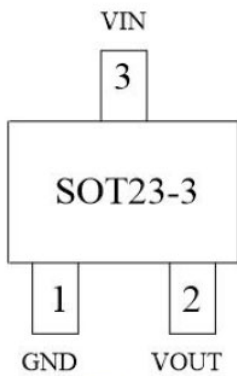
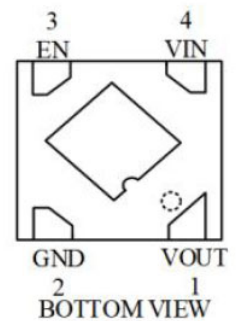
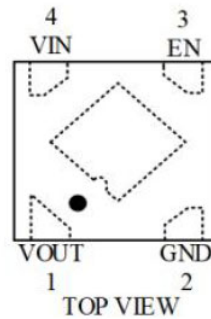
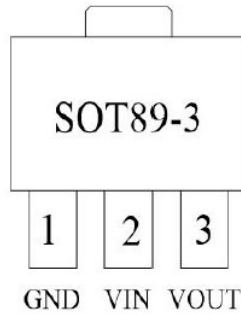
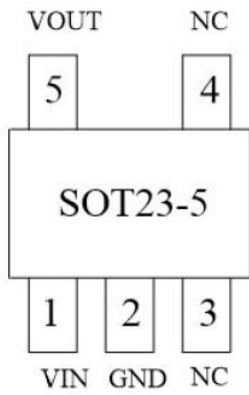


6V, Low-Dropout Voltage Regulator

PSRR



Pin Configuration and Functions



Pin Functions

Name	SOT23-5	SOT89-3	SOT23-3	DFN1×1	Description
	OSU20BXXA/B TG	OSU20BXXA/B TS	OSU20BXXA/B TE	OSU20BXXA/B TN	
VIN	1	2	3	4	Input pin
GND	2	1	1	2	Ground pin
EN	3			3	Enable pin
NC	4				No connection
VOUT	5	3	2	1	Output pin

Absolute Maximum Ratings

Parameter	Description	Min	Max	Unit
Input voltage	VIN to GND	-0.3	6	V
	VOUT to GND	-0.3	5	V
	VIN to VOOUT	-0.3	5	V
	EN to GND	-0.3	6	V
Current	Peak output current	Internally limited		
Temperature	Operating temperature range	-40	125	°C
	Storage temperature	-40	150	°C
Thermal resistance (Junction to ambient)	SOT89-3	130		°C/W
	DFN1×1	300		
	SOT23-5	200		
	SOT23-3	200		
Power dissipation	SOT89-3	900		mW
	DFN1×1	400		
	SOT23-5	600		
	SOT23-3	600		

Note:

exceeding the range specified by the rated parameters will cause damage to the chip, and the working state of the chip beyond the range of rated parameters cannot be guaranteed. Exposure outside the rated parameter range will affect the reliability of the chip.

ESD Ratings

Parameter	Description	Range	Unit
V _{ESD}	Human body model(HBM)	4	KV

Note:

JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.

Electrical Characteristics

(At $T_A=25^{\circ}\text{C}$, $C_{IN}=1\mu\text{F}$, $V_{IN}=V_{OUTNOM}+1\text{V}$, $C_{OUT}=1\mu\text{F}$, unless otherwise noted)

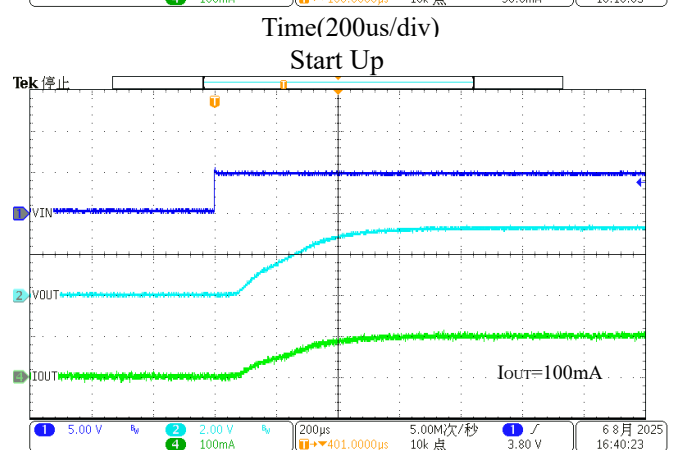
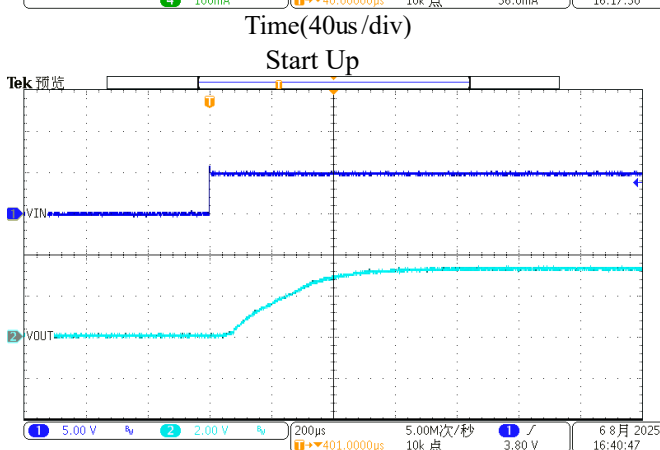
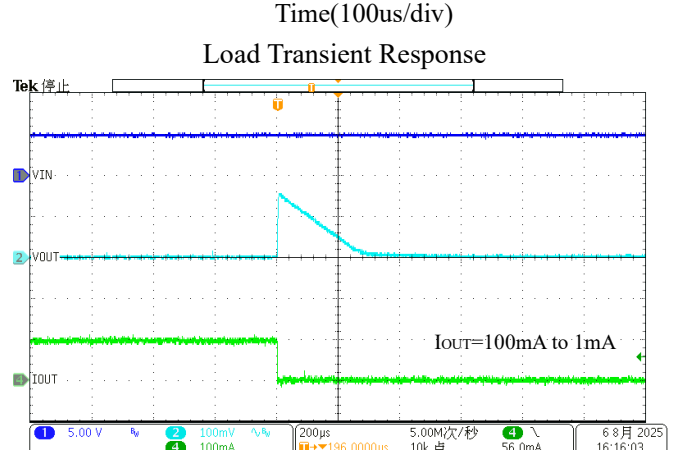
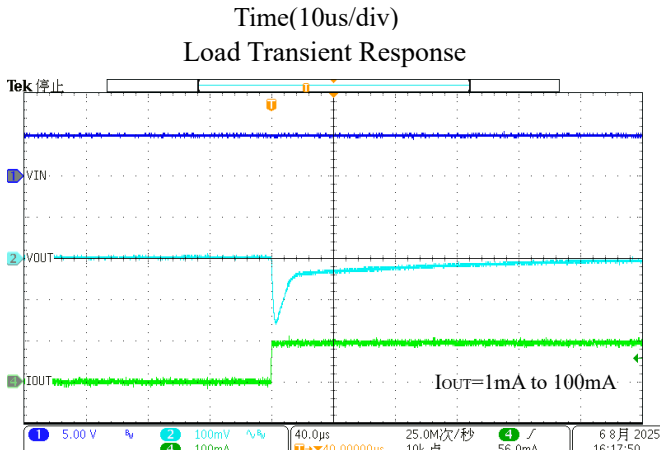
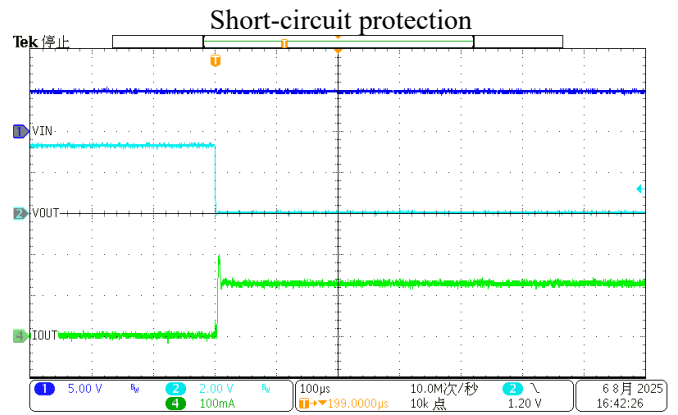
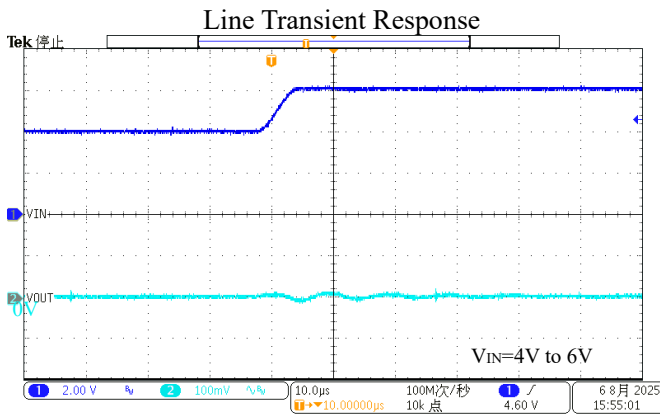
Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
V_{IN}	Operating input voltage		1.3	—	6	V
I_{GND}	Quiescent current	$V_{IN}=5\text{V}$, No load	—	800	—	nA
V_{OUT}	Output voltage	$V_{IN}=5\text{V}$, $I_{OUT}=10\text{mA}$	$V_{OUTNOM} * 0.98$	V_{OUTNOM}	$V_{OUTNOM} * 1.02$	V
I_{OUT_MAX}	Output current		500	—	—	mA
V_{DROP}	Dropout voltage	$I_{OUT}=100\text{mA}$, $V_{IN}=V_{OUTNOM}-0.1\text{V}$	—	130	—	mV
$\Delta V_{OUT}/\Delta I_{OUT}$	Load regulation	$V_{IN}=V_{OUTNOM}+1\text{V}$, $1\text{mA}\leq I_{OUT}\leq 200\text{mA}$	—	0.1	—	mV/mA
$\Delta V_{OUT}/\Delta V_{IN}$	Line regulation	$I_{OUT}=1\text{mA}$, $V_{OUTNOM}+1\text{V}\leq V_{IN}\leq 6\text{V}$	—	0.1	—	mV/V
I_{LIMIT}	Current limit	$V_{IN}=V_{OUTNOM}+1\text{V}$	—	700	—	mA
I_{SHORT}	Short current		—	120	—	mA
T_{SHDN}	Thermal shutdown temperature	Shutdown, temperature increasing	—	150	—	°C
		Reset, temperature decreasing	—	120	—	
V_{ENH}	EN high level	Enabled	1.3	—	—	V
V_{ENL}	EN low level	Shutdown	—	—	0.4	V

Note:

Dropout Voltage is the voltage difference between the input and the output at which the output voltage drops 2% below its nominal value.

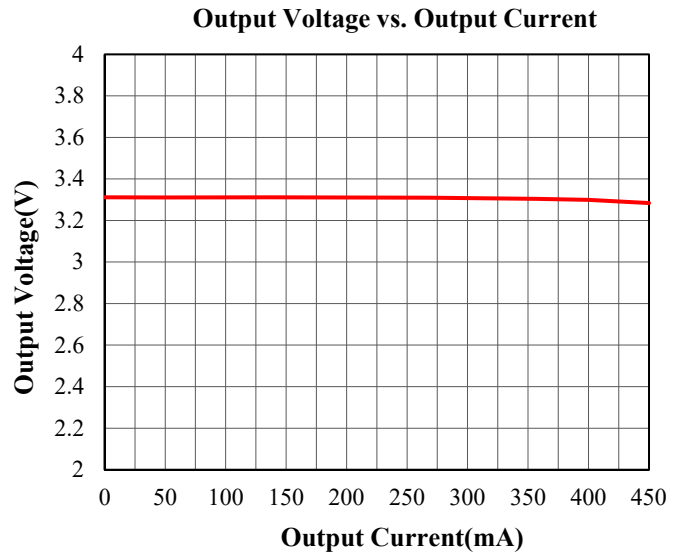
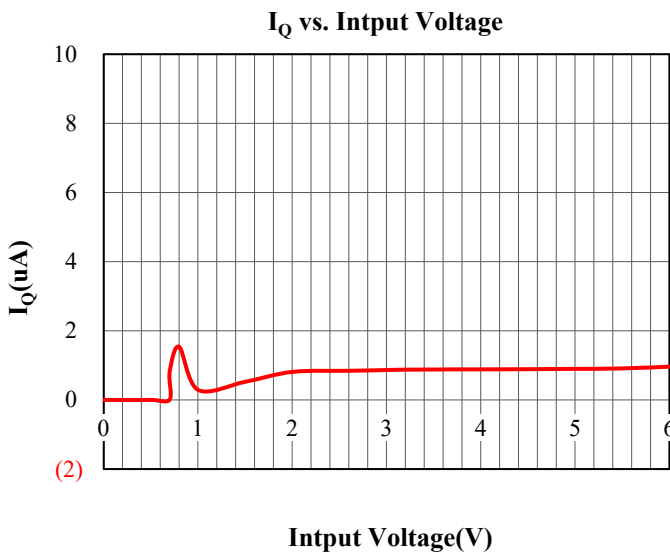
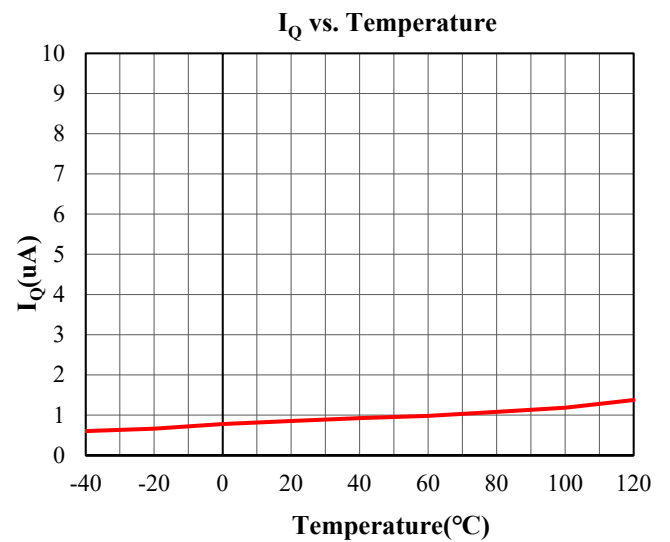
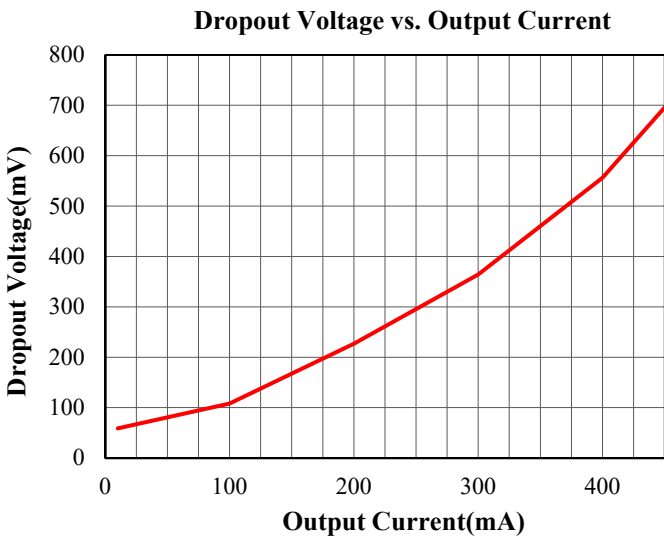
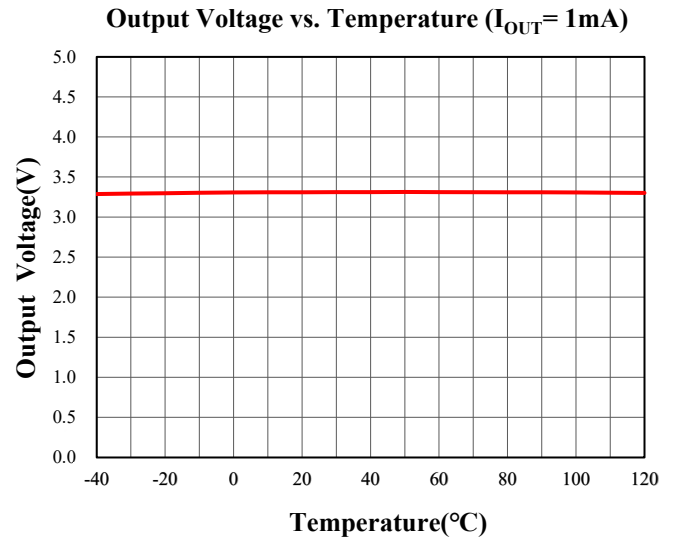
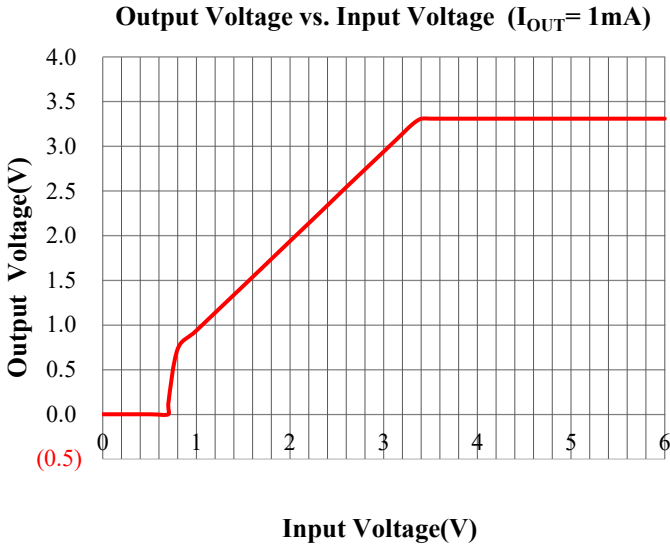
Typical Characteristics

(OSU20B33A/BTG, Test condition: $T_A=25^{\circ}\text{C}$, $C_{IN}=1\mu\text{F}$, $V_{IN}=5\text{V}$, $C_{OUT}=1\mu\text{F}$ unless otherwise note)



Typical Characteristics

(OSU20B33A/BTG, Test Condition: $T_A = 25^\circ\text{C}$, $C_{IN} = 1\mu\text{F}$, $V_{IN} = V_{OUTNOM} + 1\text{V}$, $C_{OUT} = 1\mu\text{F}$ unless otherwise note)

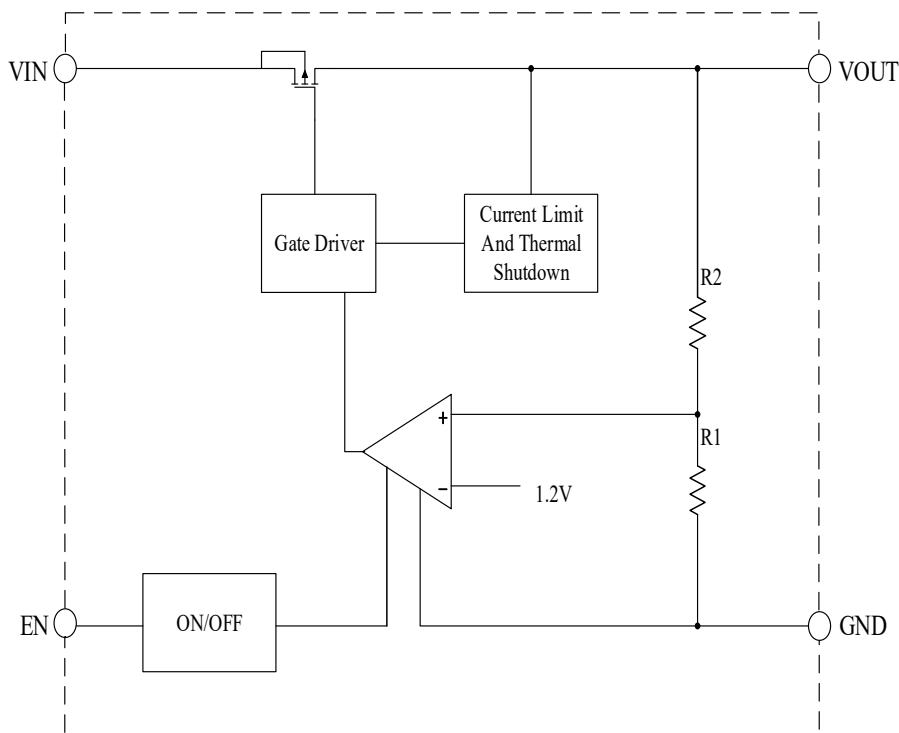


Detailed Description

Overview

The OSU20BXXA/B series is an ultra-small, low dropout (LDO) linear regulator that can source 500mA of output current. The OSU20BXXA/B has fast response to input voltage transient and load current transient, and ensures no overshoot voltage during OSU20BXXA/B startup and short circuit recovery. The OSU20BXXA/B series has thermal shutdown, current limit, and short circuit protections for added safety. The OSU20BXXA/B series contains eight fixed output voltages of 1.2V, 1.5V, 1.8V, 2.5V, 2.8V, 3.0V, 3.3V, 3.6V.

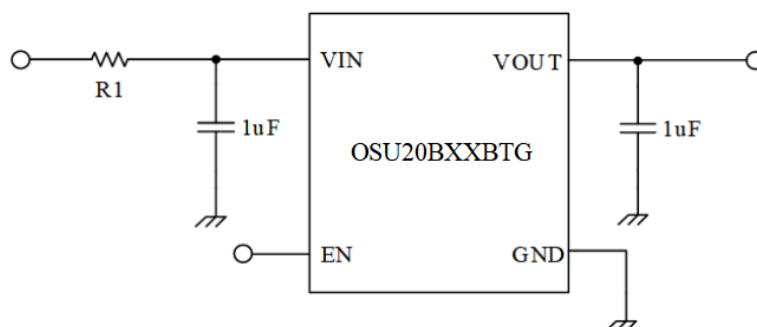
Functional Block Diagram



Functional Block Diagram

Input Capacitor and Output Capacitor

A 1 μ F ceramic capacitor is recommended to connect between VIN and GND pins to decouple input power supply glitch and noise. The amount of the capacitance may be increased without limit. This input capacitor must be located as close as possible to the device to assure input stability and less noise. For PCB layout, a wide copper trace is required for both VIN and GND.



For the stability of LDO, an output capacitor is required. The recommended minimum output capacitance is 1uF. It is recommended to use Ceramic capacitor with a temperature characteristic of X5R or X7R. A higher capacitance value helps to improve the transient response of the load/line. The output capacitance can be increased to maintain a lower down/overshoot. Place the output capacitor as close as possible to the VOUT and GND pins.

Current Limit and Short Circuit Protection

When output current at VOUT pin is higher than current limit threshold or the VOUT pin is direct short to GND, the current limit protection will be triggered and clamp the output current at a pre-designed level to prevent over-current and thermal damage.

Power Dissipation and Thermal Protection

The OSU20BXXA/B has internal thermal sense and protection circuits. When excessive power dissipation happens on the device, such as short circuit at the output pin or very heavy load current with a large voltage drop across the device, the internal thermal protection circuit will be triggered, and it will shut down the power MOSFET to prevent the LDO from damage. As soon as excessive thermal condition is removed and the temperature of the device drops down, the thermal protection circuit will lease the control of the power MOSFET, and the LDO device goes to normal operation.

Power dissipation caused by voltage drop across the LDO and by the output current flowing through the device needs to be dissipated out from the chip. The maximum junction temperature is dependent on power dissipation, package, the PCB layout, number of used Cu layers, Cu layers thickness and the ambient temperature.

During normal operation, LDO junction temperature should not exceed 150°C, or else it may result in deterioration of the properties of the chip. Using below equations to calculate the power dissipation and estimate the junction temperature.

The power dissipation can be calculated using Equation (1).

$$P_D = (V_{IN} - V_{OUT}) \times I_{OUT} \quad (1)$$

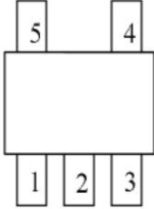
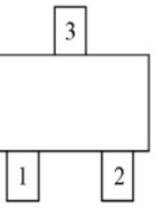
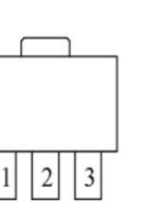
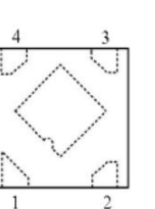
The junction temperature can be estimated using Equation . $R_{\theta JA_EVM}$ is the junction-to-ambient thermal resistance based on customer's PCB. Verify the application and allow sufficient margins in the thermal design by the Equation (2).

$$T_J = T_A + P_D \times R_{\theta JA_EVM} \quad (2)$$

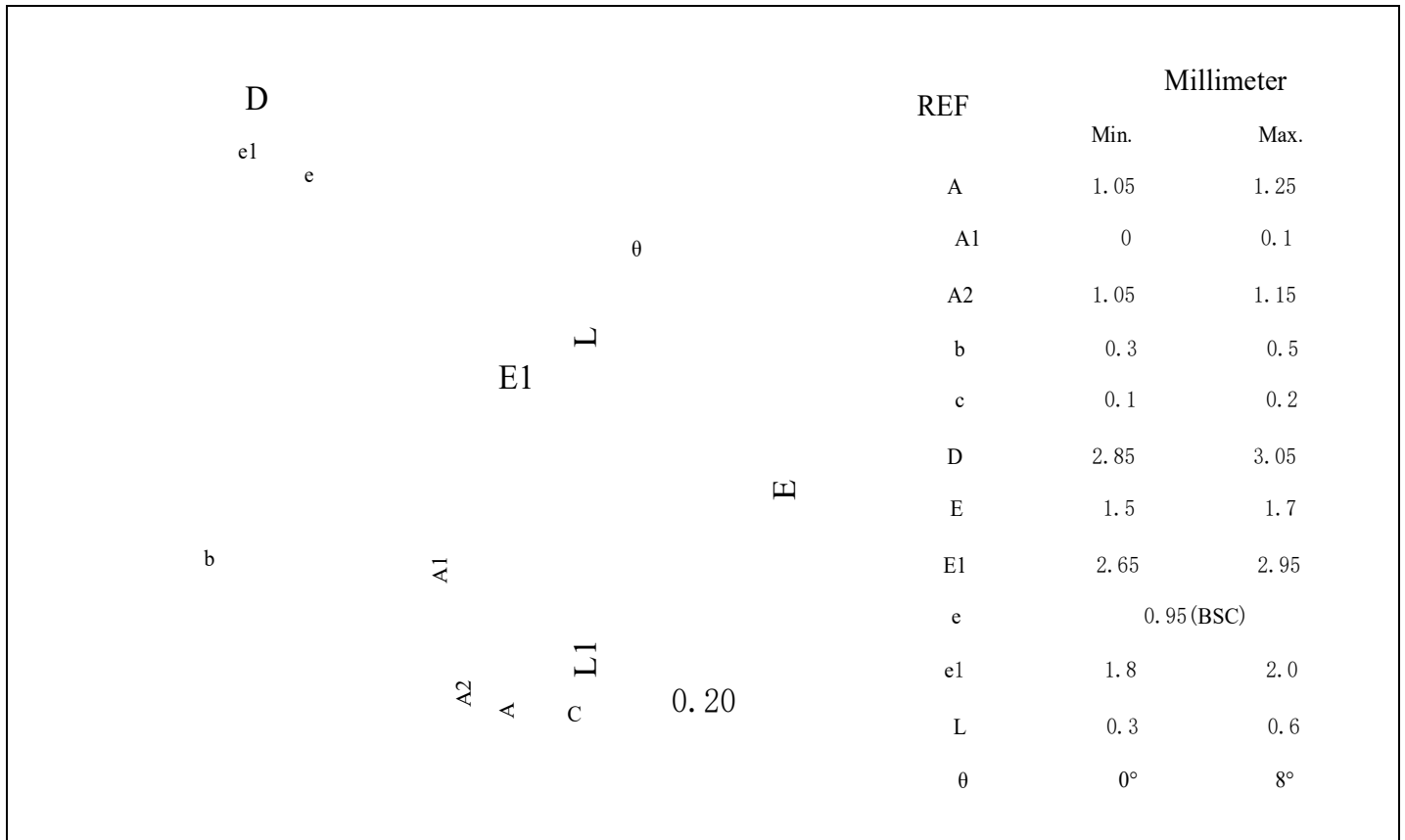
$R_{\theta JA_EVM}$ is a critical parameter and depends on many factors such as the following:

- Power dissipation
- Air temperature/flow
- PCB area
- Copper heat-sink area
- Number of thermal vias under the package
- Adjacent component placemen

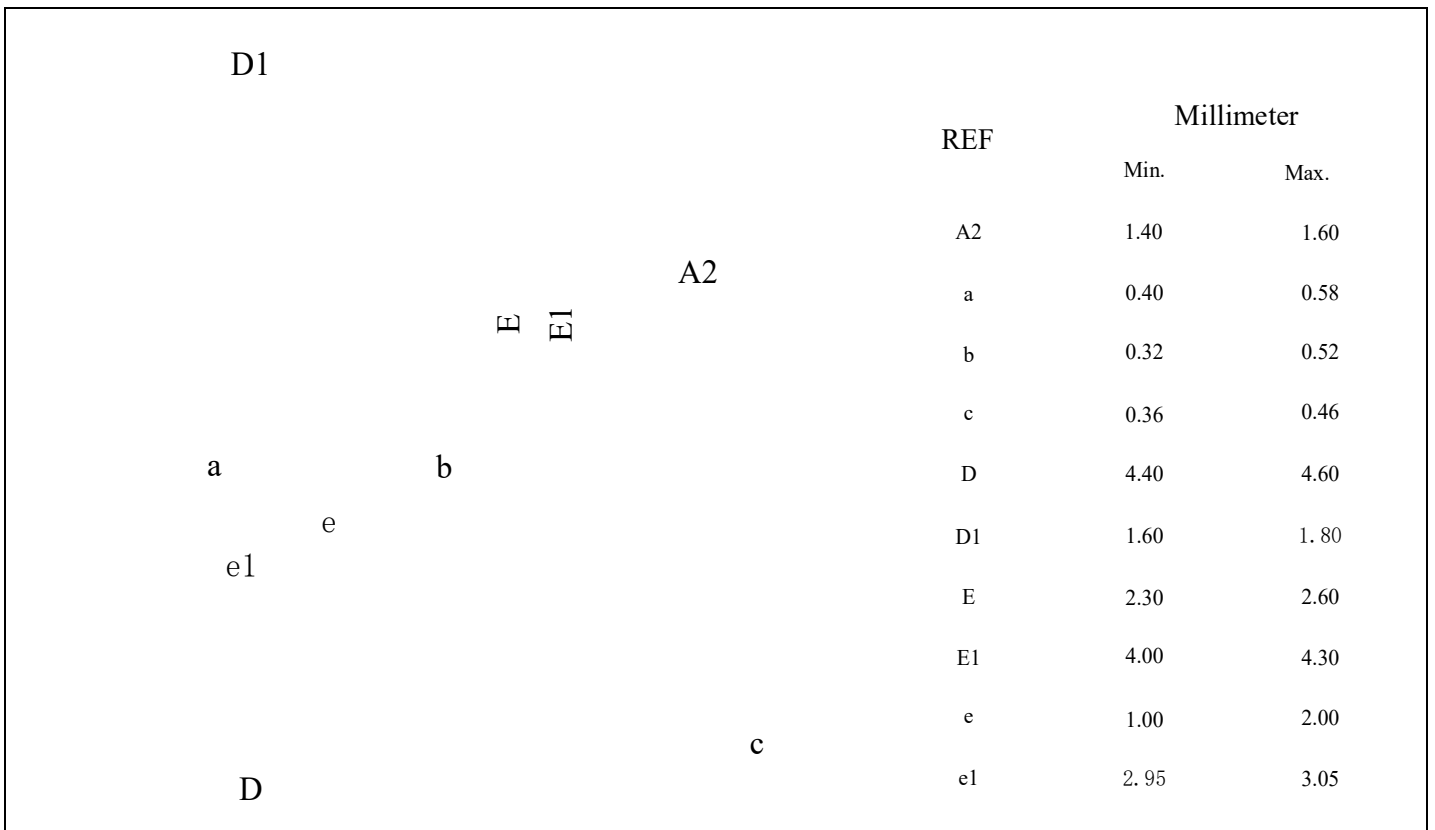
Ordering And Marking Information

Part Number					
<p>OS U20B XX X XX</p> <ul style="list-style-type: none"> └─ Package definition └─ Voltage accuracy └─ Output name └─ Product name └─ Company name 	Package Outline				
	Minimum Package	SOT23-5 3000pcs/Reel	SOT23-3 3000pcs/Reel	SOT89-3 1000pcs/Reel	DFN1×1 10000pcs/Reel
	Marking	<p>20BXX B</p> <p>└─ B: B(±2%) A(±1%) C(±3%)</p> <p>└─ 20BXX: 20B33(3.3V)</p> <p>429 X</p> <p>└─ X: Internal Code. Variable.</p> <p>└─ 429: 4-2024; 29-the 29th</p>			<p>Output voltage</p> <p>└─ XX</p> <p>└─ XX</p> <p>└─ Year and week number</p> <p>4=2024, 5=2025...</p> <p>A=week 1</p> <p>a=week 27...</p>

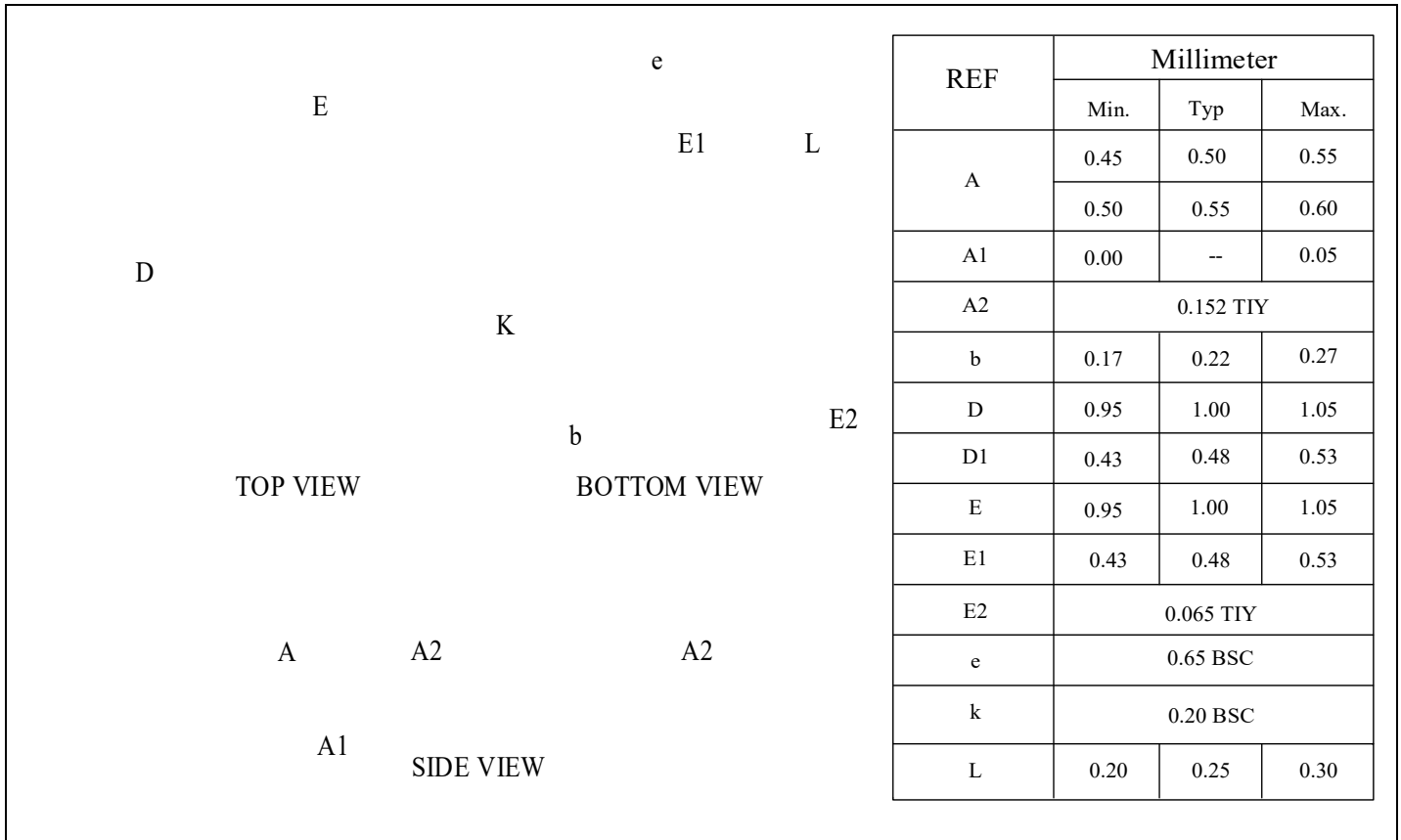
Package Outline
SOT23-5



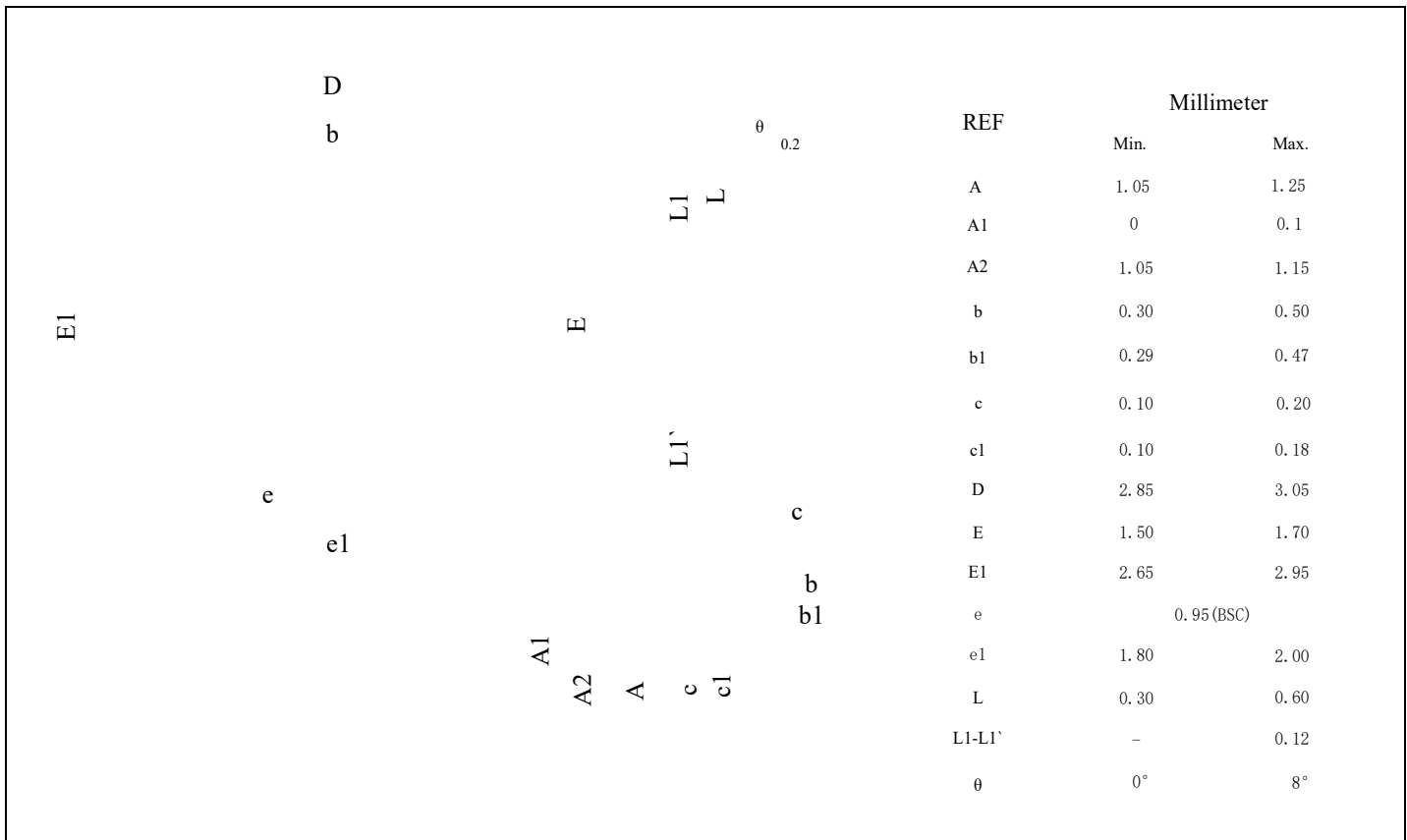
SOT89-3



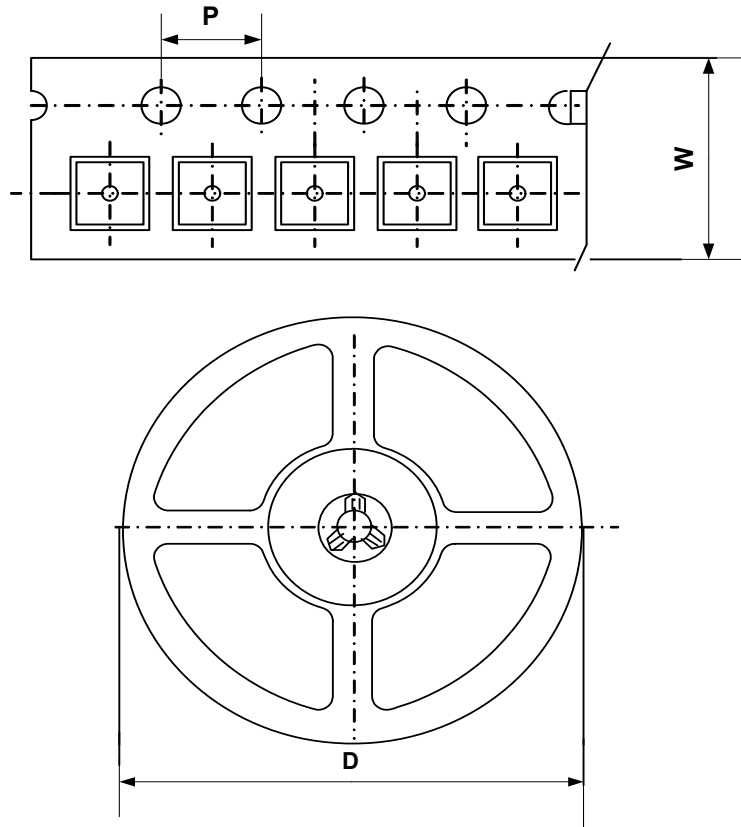
DFN1×1



SOT23-3



Packing Information



Type	W(mm)	P(mm)	D(mm)	Qty (pcs)
SOT23-5	8.0mm	4.0mm	178.0mm	3000pcs
SOT89-3	12.0mm	4.0mm	178.0mm	1000pcs
DFN1×1	8.0mm	4.0mm	178.0mm	10000pcs
SOT23-3	8.0 mm	4.0mm	178.0mm	3000pcs

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